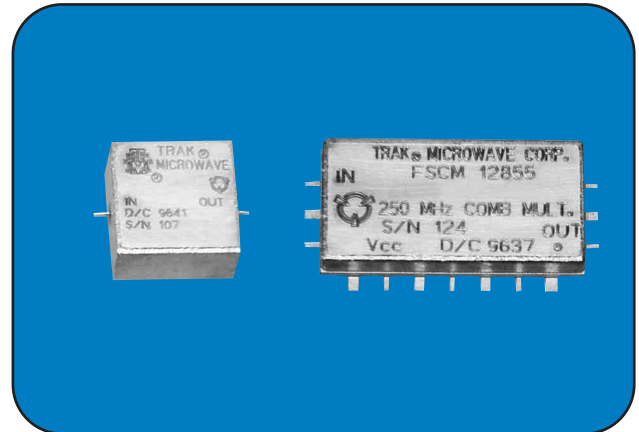


**Features:**

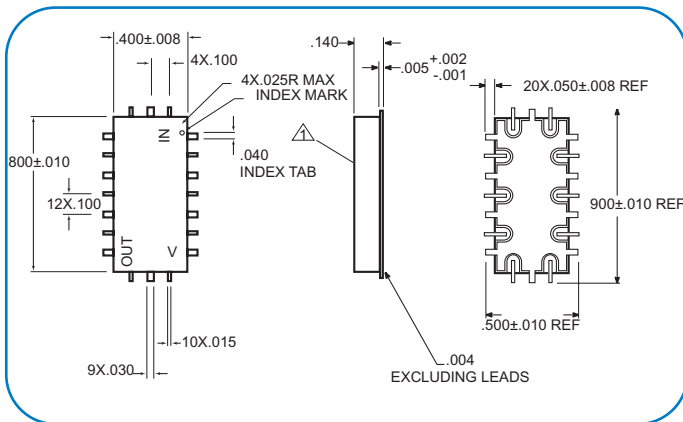
- Small SMT or Drop-In Packages
- Optimized for Maximum RF Power
- Active and Passive Designs
- Tape and Reel Compatible
- Good Phase Noise
- Withstand + 230 °C for Reflow
- Low DC Power Consumption
- Input Amplifier on Active Designs



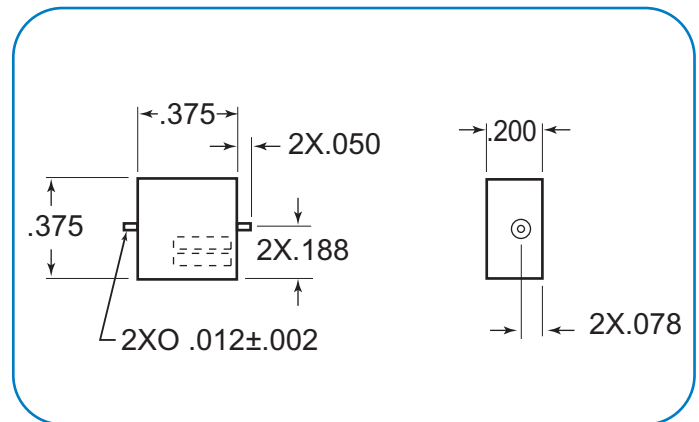
Electrical Specifications			
Input	Unit A	Unit B	Unit C
Operating Freq.(MHz):	31.25 ±1%	100 ±1%	250 ±1%
Power Level:(typical)	CMOS	+23 dBm	+12 dBm
<b>Output</b>			
Operating Frequency:			
Lower Limit (MHz)	875	100	1500
Upper Limit (MHz)	1187.5	3000	4750
Power Level:(dBm, typical)			
	-17 to -27	-20 to -25	-20 to -30
Power Variation: (Adjacent Combs)			
	3 dB,max.	3 dB,max.	3 dB,max.
DC Power: (V)	+12 ± 1.5%	none	+12±1.5%
Current: (nominal)	80 mA	none	80 mA
Power Consumption: (nominal)			
	0.96 W	none	0.96 W

Environmental Specifications			
Operating Temp.:	- 10 to + 71 °C, baseplate		
*Extended Operating Temp.:	- 34 to + 95 °C, baseplate		
Maximum Reflow Temp.:	+ 230 °C for 20 seconds		
Environment:	Space		
Mechanical Specifications			
	Unit A	Unit B	Unit C
Package Drawing:	A	B	A
Weight: (nominal)	0.15 oz	0.25 oz	0.15 oz
	4.3 g	7.1 g	4.3 g
Connectors:	Pins	Pins	Pins

\* Performance may vary over the extended operating temperatures.



Package A



Package B

Specifications subject to change without notice.